

AMENDMENTS TO THE SPECIFICATION

In the Title:

Please amend the title as follows:

Solid ~~High~~ Polymer Type Cell Assembly

In the Specification:

Page 1, line 2, after the title, please insert the following new paragraph:

Related Applications

This application is a 35 U.S.C. 371 national stage filing of International Application No. PCT/JP2003/008098, filed 26 June 2003, which claims priority to Japan Patent Application No. 2002-186093 filed on 26 June 2002, in Japan. The contents of the aforementioned applications are hereby incorporated by reference.